

3.5 x 2.8 mm SMD CHIP LED LAMP



Features

• Ideal for indication light on hand held products

• Long life and robust package

• Variety of lens types and color choices available

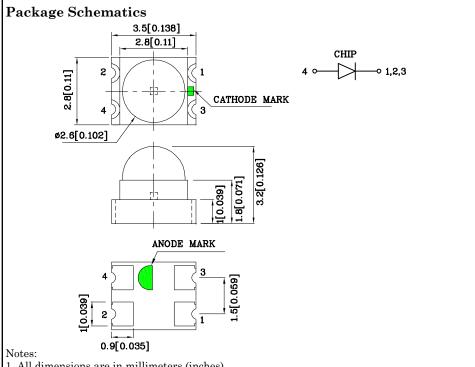
ullet Package: 500pcs / reel

• Moisture sensitivity level : level 3

• RoHS compliant







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	MDK (AlGaInP)	Unit		
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	50	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	185	mA	
Power Dissipation	P_{D}	130	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	C	

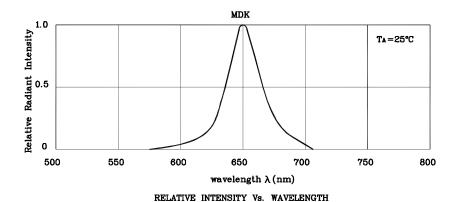
Operating Characteristics T _A =25°C)		MDK (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =50mA)	V_{F}	2.1	V	
Forward Voltage (Max.) (I _F =50mA)	V_{F}	2.6	V	
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA	
Wavelength of Peak Emission (Typ.) $(I_F=50 \text{mA})$	λΡ	650	nm	
Wavelength of Dominant Emission (Typ.) $(I_F=50 \text{mA})$	λD	630	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =50mA)	$\triangle \lambda$	28	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	35	рF	

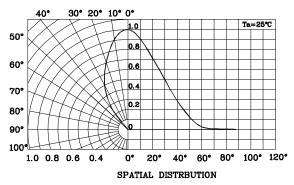
Part Number	Emitting Color	Emitting Material	Lens-color	Inter (I _F =5	inous nsity 0mA) cd	Wavelength nm λP	Viewing Angle 2θ 1/2
				min.	typ.		
XZMDK45W50MAV-6	Red	AlGaInP	Water Clear	1200	1890	650	60°

Apr 21,2011 XDSB4727 V2 Layout: Maggie L.

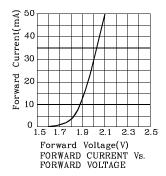


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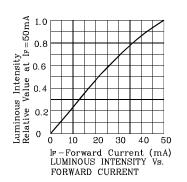


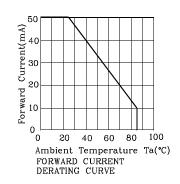


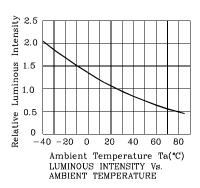
❖ MDK



www.SunLEDusa.com

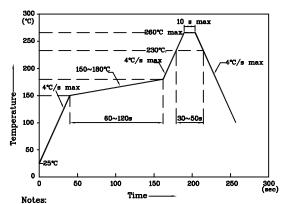






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

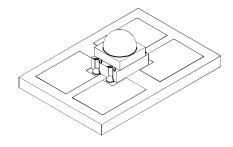


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- Do not put stress to the epoxy resin during high temperatures conditions

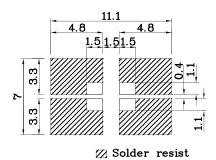




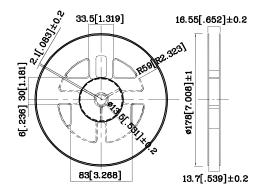
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



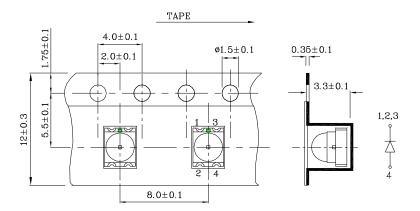
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

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- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

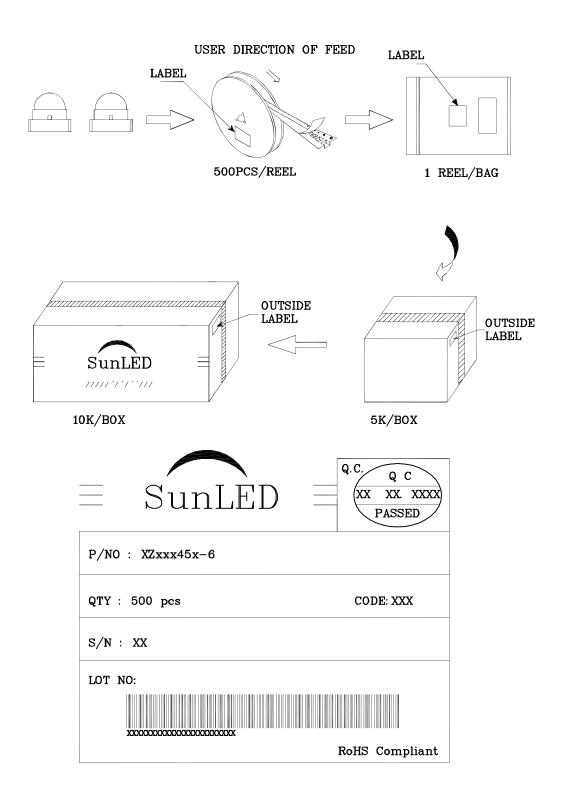
Note: Accuracy may depend on the sorting parameters.

XDSB4727 V2 Layout: Maggie L.





PACKING & LABEL SPECIFICATIONS



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